Preface

Dear Distinguished Delegates and Guests,

The Organizing Committee warmly welcomes you to the 2014 International Conference on Materials Engineering and Automatic Control (ICMEAC 2014), held on May 26-28, 2014 in Singapore. ICMEAC 2014 is held on conjunction with 2014 2nd International Conference on Mechanical, Automotive and Materials Engineering (CMAME 2014), which is sponsored by Tianjin University of Technology and Singapore Institute of Electronics.

The conference is aimed at providing a platform for all of you to present leading-edge work in the fields of Materials Engineering and Automatic Control. More than 350 papers were and finally 182 papers are accepted for the conference after peer reviewed by reviewers drawn from the scientific committee, external reviewers and editorial board depending on the subject matter of the paper. Reviewing and initial selection were undertaken electronically. After the peer-review process, the submitted papers were selected on the basis of originality, significance, and clarity for the purpose of the conference. The selected papers and additional late-breaking contributions to be presented as lectures will make an exciting technical program. The conference program is extremely rich, featuring high-impact presentations.

The proceeding records the fully refereed papers presented at the conference. The main conference themes and tracks are Electrical Engineering, Materials Research, Control Engineering, Manufacturing Technology, Power System, Robotics and System Modeling. The main goal of the conference is also to provide international scientific forums for exchange of new ideas focus on Materials Engineering and Automatic Control.

We would like to thank the program chairs, organization staff, and the members of the program committees for their work. Thanks also go to all those who have contributed to the success of the conference.

Hopefully, all participants and other interested readers benefit scientifically from the proceedings and also find it stimulating in the process. We hope all of you have a unique, rewarding and enjoyable week in Singapore.

With our warmest regards,

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